

N-Channel 30 V (D-S) MOSFET

PRODUCT SUMMARY

V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^{a, e}	Q _g (Typ.)
30	0.0025 at V _{GS} = 10 V	95	42 nC
	0.0046 at V _{GS} = 4.5 V	70	

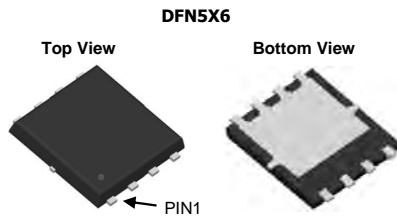
FEATURES

- DT-Trench Power MOSFET
- 100 % R_g and UIS Tested

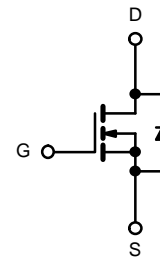
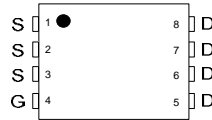


APPLICATIONS

- OR-ing
- Server
- Notebook PC Core



Top View



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C, unless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	30	V	
Gate-Source Voltage	V _{GS}	± 20		
Continuous Drain Current (T _J = 175 °C)	I _D	T _C = 25 °C	95 ^{a, e}	
		T _C = 70 °C	80 ^e	
		T _A = 25 °C	30 ^{b, c}	
		T _A = 70 °C	21 ^{b, c}	
Pulsed Drain Current	I _{DM}	360	A	
Avalanche Current Pulse	L = 0.1 mH	I _{AS}		86
Single Pulse Avalanche Energy	E _{AS}	59		mJ
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C	95 ^{a, e}	
		T _A = 25 °C	3.1 ^{b, c}	
Maximum Power Dissipation	P _D	T _C = 25 °C	240 ^a	
		T _C = 70 °C	155	
		T _A = 25 °C	3.62 ^{b, c}	
		T _A = 70 °C	2.43 ^{b, c}	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^{b, d}	R _{thJA}	35	40	°C/W
Maximum Junction-to-Case	R _{thJC}	0.5	0.8	

Notes:

a. Based on T_C = 25 °C.

b. Surface mounted on 1" x 1" FR4 board.

c. t = 10 s.

d. Maximum under steady state conditions is 90 °C/W.

e. Calculated based on maximum junction temperature. Package limitation current is 95 A.

SPECIFICATIONS ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted)

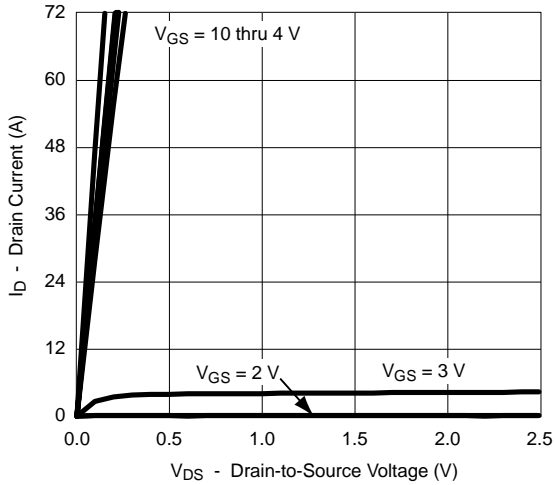
Parameter	Symbol	Test Conditions	Min .	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	30			V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	$I_D = 250\text{ }\mu\text{A}$		35		mV/ $^\circ\text{C}$
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			-7.5		
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	1		3	V
Gate-Source Leakage	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 24\text{ V}, V_{GS} = 0\text{ V}$			1	μA
		$V_{DS} = 24\text{ V}, V_{GS} = 0\text{ V}, T_J = 55\text{ }^\circ\text{C}$			10	
On-State Drain Current ^a	$I_{D(on)}$	$V_{DS} \geq 5\text{ V}, V_{GS} = 10\text{ V}$	120			A
Drain-Source On-State Resistance ^a	$R_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = 30\text{ A}$		0.0025	0.0030	Ω
		$V_{GS} = 4.5\text{ V}, I_D = 20\text{ A}$		0.0046	0.0055	
Forward Transconductance ^a	g_{fs}	$V_{DS} = 15\text{ V}, I_D = 30\text{ A}$		155		S
Dynamic^b						
Input Capacitance	C_{iss}	$V_{DS} = 24\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$		4765		pF
Output Capacitance	C_{oss}			1025		
Reverse Transfer Capacitance	C_{rss}			570		
Total Gate Charge	Q_g	$V_{DS} = 24\text{ V}, V_{GS} = 10\text{ V}, I_D = 30\text{ A}$		42		nC
		$V_{DS} = 24\text{ V}, V_{GS} = 4.5\text{ V}, I_D = 20\text{ A}$		29		
Gate-Source Charge	Q_{gs}	$V_{DS} = 24\text{ V}, V_{GS} = 4.5\text{ V}, I_D = 20\text{ A}$		10		
Gate-Drain Charge	Q_{gd}			14		
Gate Resistance	R_g	$f = 1\text{ MHz}$		1.5	2.5	Ω
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 24\text{ V}, R_L = 0.555\text{ }\Omega$ $I_D \cong 30\text{ A}, V_{GEN} = 10\text{ V}, R_g = 1\text{ }\Omega$		23		ns
Rise Time	t_r			11		
Turn-Off Delay Time	$t_{d(off)}$			60		
Fall Time	t_f			13		
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 15\text{ V}, R_L = 0.625\text{ }\Omega$ $I_D \cong 24\text{ A}, V_{GEN} = 4.5\text{ V}, R_g = 1\text{ }\Omega$		50		
Rise Time	t_r			166		
Turn-Off Delay Time	$t_{d(off)}$			47		
Fall Time	t_f			11		
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I_S	$T_C = 25\text{ }^\circ\text{C}$			95	A
Pulse Diode Forward Current ^a	I_{SM}				360	
Body Diode Voltage	V_{SD}	$I_S = 22\text{ A}$		0.7	1.2	V
Body Diode Reverse Recovery Time	t_{rr}	$I_F = 20\text{ A}, di/dt = 100\text{ A}/\mu\text{s}, T_J = 25\text{ }^\circ\text{C}$		50	82	ns
Body Diode Reverse Recovery Charge	Q_{rr}			70	98	nC
Reverse Recovery Fall Time	t_a			20		ns
Reverse Recovery Rise Time	t_b			28		

Notes:

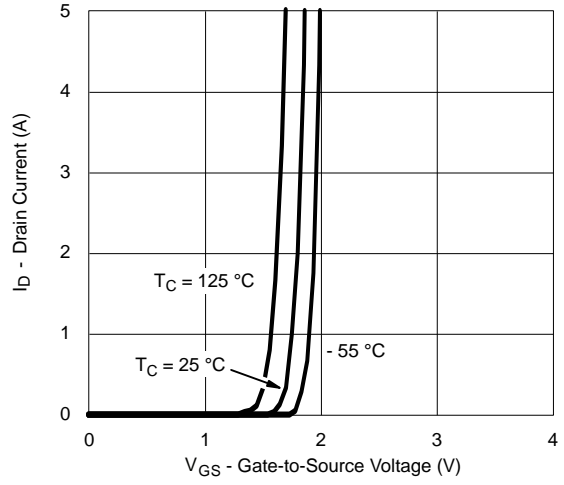
- Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.
- Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

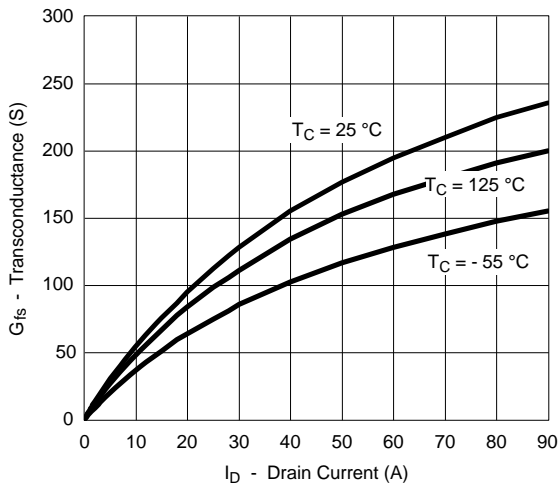
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



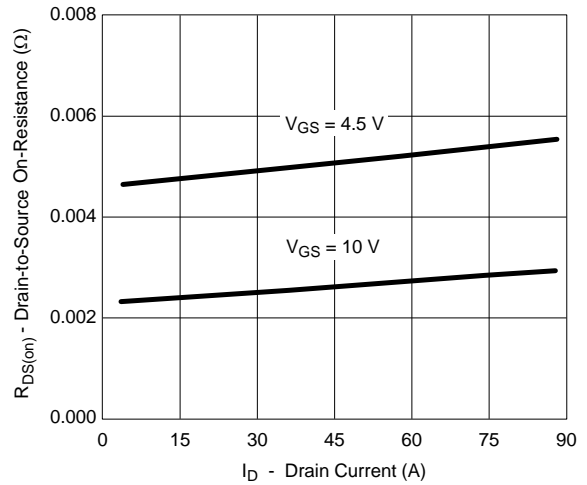
Output Characteristics



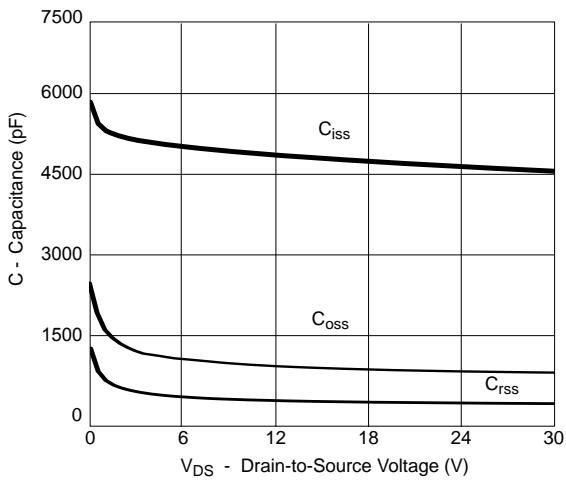
Transfer Characteristics



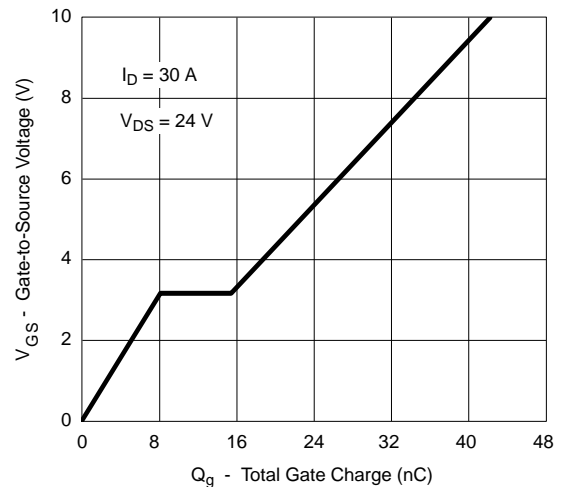
Transconductance



$R_{DS(on)}$ vs. Drain Current

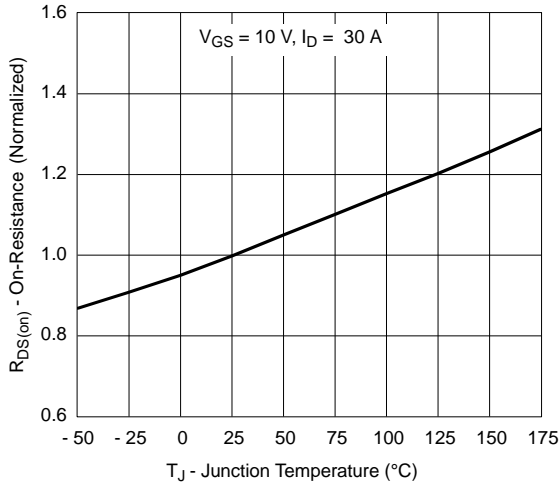


Capacitance

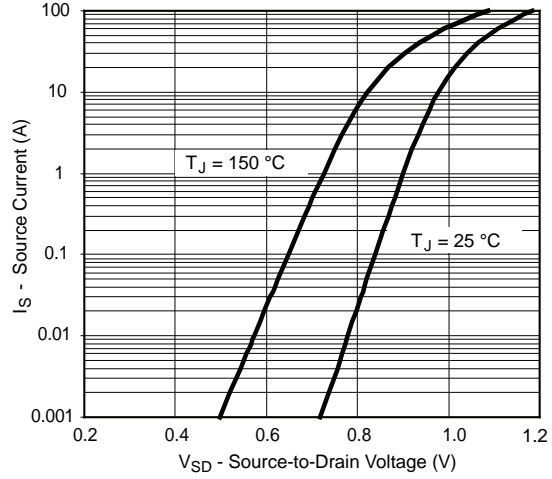


Gate Charge

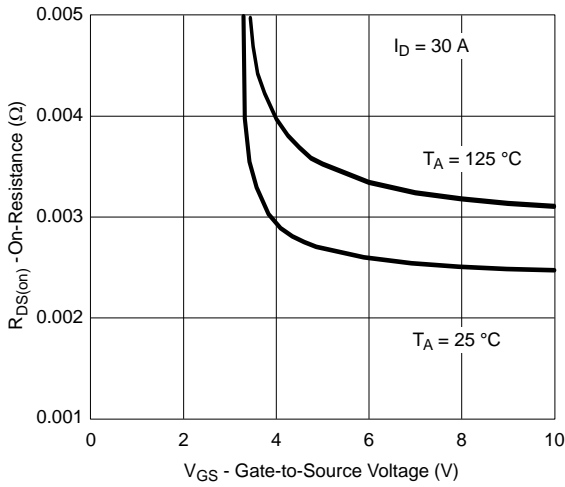
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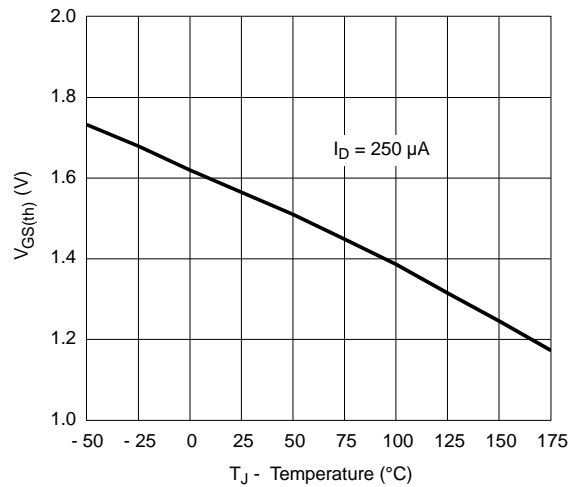
On-Resistance vs. Junction Temperature



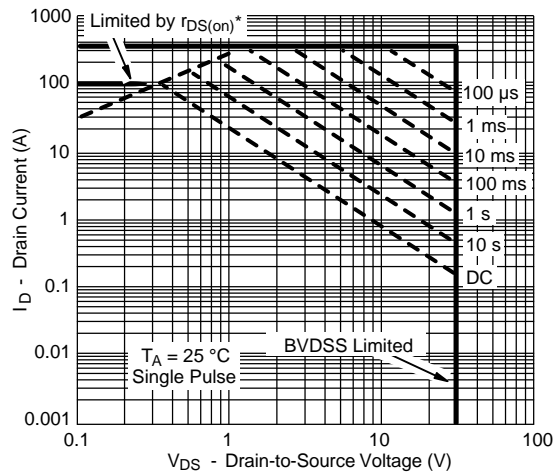
Forward Diode Voltage vs. Temperature



R_{DS(on)} vs. V_{GS} vs. Temperature

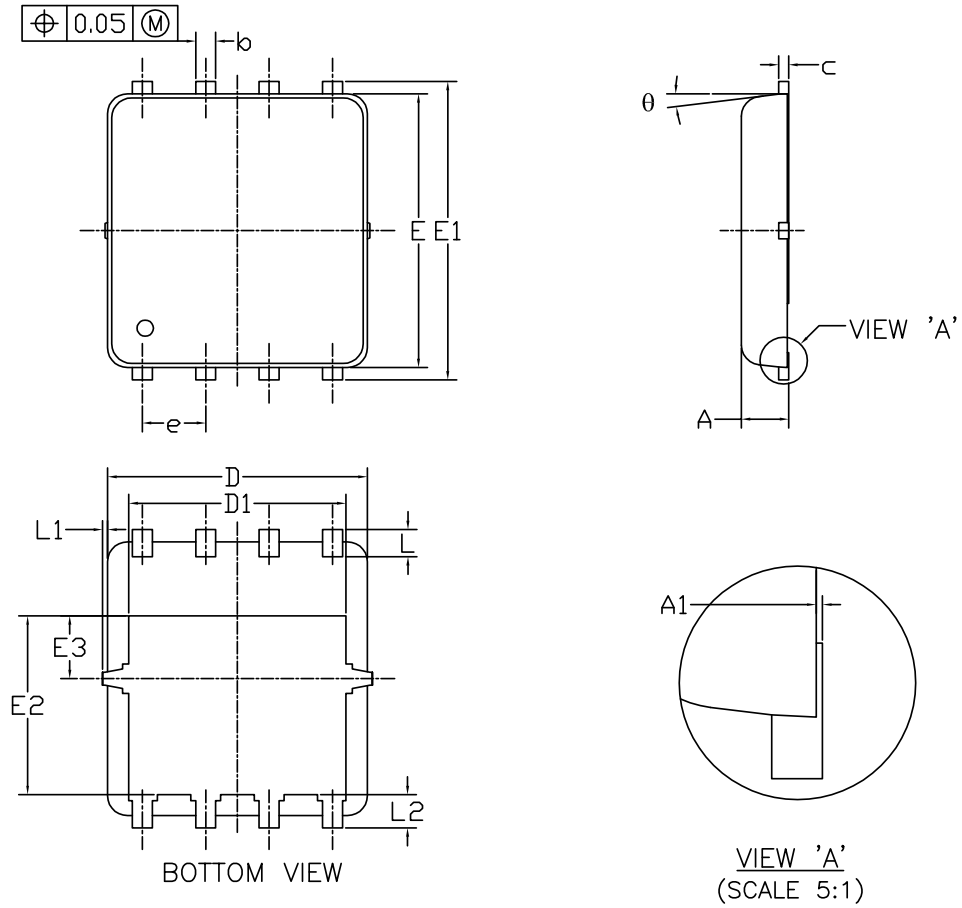


Threshold Voltage

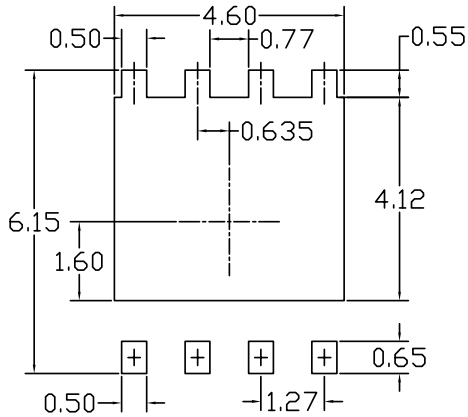


*V_{GS} > minimum V_{GS} at which r_{DS(on)} is specified
Safe Operating Area, Junction-to-Ambient

DFN5x6_8L_EP1_P PACKAGE OUTLIN



RECOMMENDED LAND PATTERN



SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.85	0.95	1.00	0.033	0.037	0.039
A1	0.00	---	0.05	0.000	---	0.002
b	0.30	0.40	0.50	0.012	0.016	0.020
c	0.15	0.20	0.25	0.006	0.008	0.010
D	4.80	5.20	5.30	0.201	0.205	0.209
D1	4.25	4.35	4.45	0.167	0.171	0.175
E	5.45	5.55	5.65	0.215	0.219	0.222
E1	5.95	6.05	6.15	0.234	0.238	0.242
E2	3.525	3.625	3.725	0.139	0.143	0.147
E3	1.175	1.275	1.375	0.046	0.050	0.054
e	1.27 BSC			0.050 BSC		
L	0.45	0.55	0.65	0.018	0.022	0.026
L1	0	---	0.15	0	---	0.006
L2	0.68 REF			0.027 REF		
θ	0°	---	10°	0°	---	10°

NOTE

UNIT: mm

1. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
MOLD FLASH AT THE NON-LEAD SIDES SHOULD BE LESS THAN 6 MILS EACH.
2. CONTROLLING DIMENSION IS MILLIMETER.
CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.

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